

QSFP DD

Amphenol ICC's QSFP DD interconnect system is comprised of a 76-position, 0.8mm pitch connector built for use in high speed serial applications. Each port supports up to 400 Gb/s in aggregate over an 8 x 50 Gb/s electrical interface. The cage and connector design provides backwards compatibility to QSFP28 modules which can be inserted into a QSFP DD port and connected to 4 of the 8 electrical channels. It is one of the industry's leading multi-lane pluggable form factors used across Ethernet, Fibre Channel and InfiniBand.



TECHNICAL INFORMATION

MATERIAL

- Housing: Black color, Glass reinforced, Lead
 Free Solder Reflow Process Compatible Thermo
 Plastic
- Contacts Base Material: Phosphor Bronze
- Plating Solder Tails: Matte tin
- Plating Mating Area: Gold
- Resonance Dampening Feature: Conductive Polymer

MECHANICAL PERFORMANCE

- Durability: 100 mating cycles
- Mating Force: 90 N max.
- PCB Thickness (Cage): 1.44 mm min. for singlemounted (1xN)
- Belly to Belly (Cage): 2.85 mm min. for 1xN
- Unmating Force (Cage): 50 N max.
- Insertion Force to PCB (Cage):
 - 780 N for 1 port
- 1000 N for 2 Ports
- 1700 N for 4 Ports
- 2400 N for 6 Ports

ELECTRICAL PERFORMANCE

- Operating Voltage: 30 VDC per contact
- Operating Current: 0.5 A per signal contact
- Differential Impedance: $100\Omega + /- 10\Omega$

ENVIRONMENTAL

- Operating and (Storage) Temperature: -40° to +85° C
- RoHS & Halogen-Free

TOOLING INFORMATION

- Cage Mounting: Thru Bezel
- EMI Options: Spring Fingers
- Configurations:
- 1XN (N=1,2,3,4,5,6)
- 2XN (N=1,2)

TARGET MARKETS/APPLICATIONS



Cellular infrastructure Network Interface Cards SAN-Storage Attached Networks



Hubs Switch Servers

QSFP DD

PART NUMBER SELECTOR

